



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Toshihiko FUJI et al.

Group Art Unit.: 1756

Serial No.: 09/772,001

Examiner: SAGAR, Kripa

Filed: January 30, 2001

For: SURFACE TREATMENT AGENT FOR RESIST PATTERN AND PATTERNING PROCESS

REPLY

Assistant Commissioner for Patents
Washington, D.C. 20231

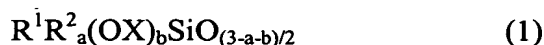
SIR:

In response to the Office Action mailed July 2, 2002, please amend the claims as follows and consider the remarks.

In the Claims

Please amend the claims as follows:

1. (Amended) A surface treatment agent which, when applied to a substrate prior to formation of a resist pattern thereon, strengthens adhesion between the substrate and the resist pattern, the surface treatment agent consisting essentially of at least one compound of the following compositional formula:



wherein R^1 is a $-(CH_2)_nY$ moiety in which Y is epoxycyclohexyl, glycidoxo, N- β -aminoethylamino, amino, N-phenylamino, mercapto or isocyanate, and n is an integer from 0 to 4; R^2 is a monovalent hydrocarbon group of 1 to 4 carbons; X is hydrogen or a monovalent hydrocarbon group of 1 to 4 carbons; "a" is 0 or 1, and "b" is 0, 1 or 2 when "a" is 0, and "b" is 0 or 1 when "a" is 1, and a solvent selected from the group consisting of alcohols, aromatic

I hereby certify that this correspondence is being deposited with the U.S. Postal Services as First Class Mail in an envelope addressed To: Commissioner of Patents and Trademarks, Washington, D.C. 20231 On: October 2, 2002
Name: Sagar Kripa
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